

Abstract

Disclosed are methods for making microwave circuits using thickfilm components, the thickfilm components including: a first, multi-layer thickfilm dielectric deposited on a ground plane; a thickfilm conductor deposited on the
5 first thickfilm dielectric; a second, multi-layer thickfilm dielectric deposited on the first dielectric and conductor to encapsulate the conductor; a thickfilm ground shield layer deposited over the first and second dielectrics; and thickfilm resistors deposited in close proximity to the first and second
10 dielectrics.